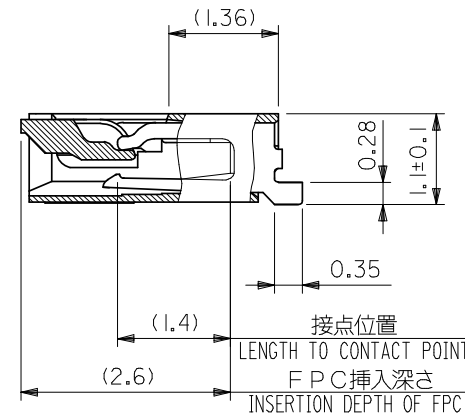
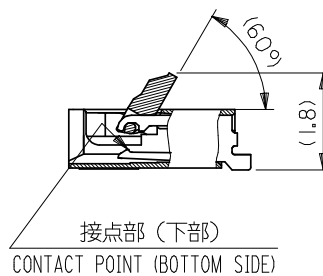
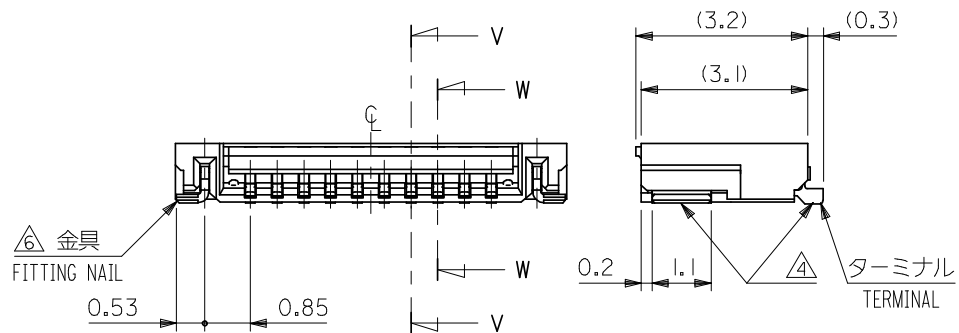


断面 V-V 奇数極  
SECT. V-V (Scale 15:1) (ODD CIRCUIT)



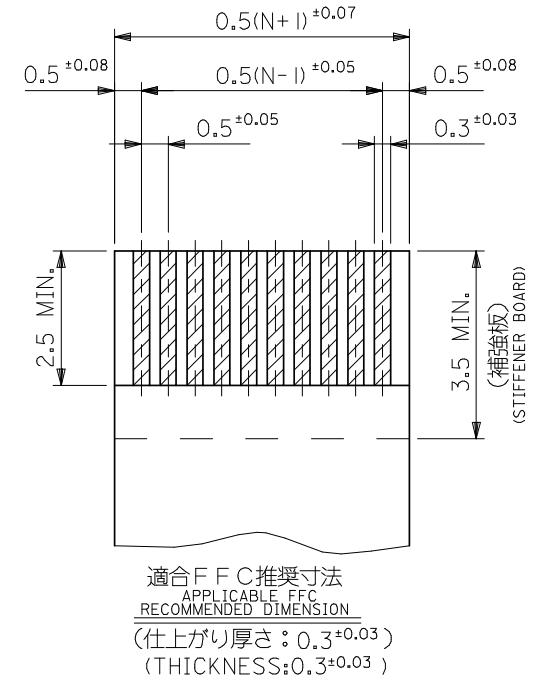
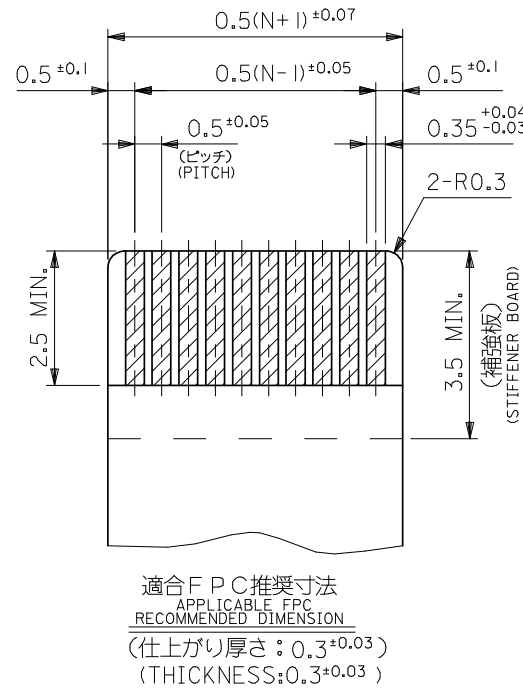
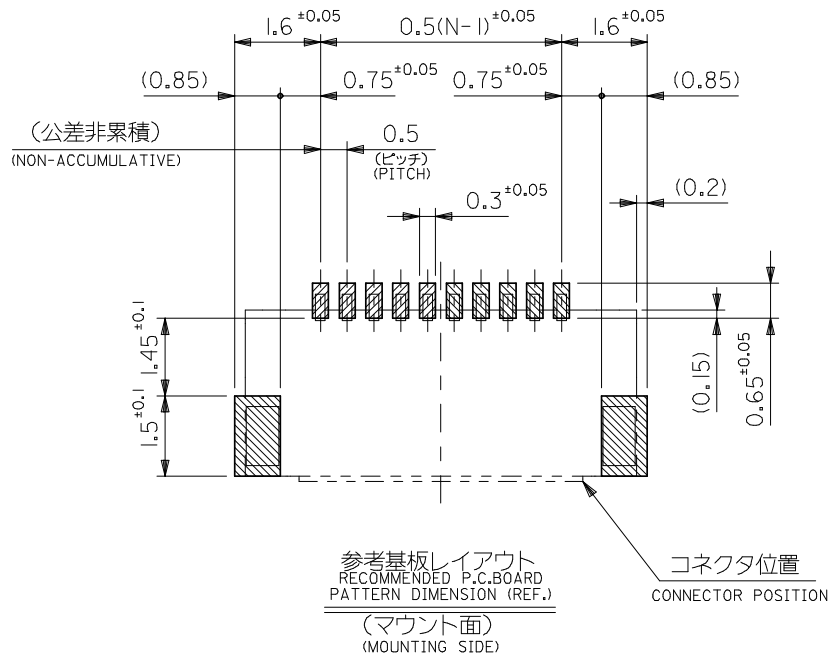
断面 W-W 偶数極  
SECT. W-W (Scale 15:1) (EVEN CIRCUIT)



(アクチュエータが開いた状態)  
(WHEN ACTUATOR IS OPENED)

12.3	11.5	14.3	51441-2493	51441-2441	24
11.3	10.5	13.3	51441-2293	51441-2241	22
10.3	9.5	12.3	51441-2093	51441-2041	20
9.3	8.5	11.3	51441-1893	51441-1841	18
8.8	8.0	10.8	51441-1793	51441-1741	17
8.3	7.5	10.3	51441-1693	51441-1641	16
6.8	6.0	8.8	51441-1393	51441-1341	13
6.3	5.5	8.3	51441-1293	51441-1241	12
5.8	5.0	7.8	51441-1193	51441-1141	11
5.3	4.5	7.3	51441-1093	51441-1041	10
4.8	4.0	6.8	51441-0993	51441-0941	9
4.3	3.5	6.3	51441-0893	51441-0841	8
3.8	3.0	5.8	51441-0793	51441-0741	7
3.3	2.5	5.3	51441-0693	51441-0641	6
C	B	A	EMBOSSED TAPE	製品番号	極数
			ORDER No. オーダー番号	MATERIAL No.	CIRCUIT
			51441-***41	MODEL NO.	
			SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			TITLE		
			0.5 FPC CONN. E/O HSG ASSY BTM CONT(H=1.1) -LEAD FREE-		
			MOLEX INCORPORATED		
			MATERIAL NO.	DOCUMENT NO.	SHEET NO.
			SEE TABLE	SD-51441-007	1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

REVISED EC NO: J2008-4048 DRWN:MNABEI 2008/06/13 CHKD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE 0.5 FPC CONN. E/O HSG ASSY BTM CONT(H=1.1) -LEAD FREE-					
	10 OVER 30 UNDER	±0.25	M. HAYASHI	2003/12/22						
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED					
	ANGULAR	±3 °	K. TOJO	2003/12/22						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
			M. SASAO	2003/12/22	SEE TABLE		SD-51441-007		1 OF 2	



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー ガラス充填, UL94V-0 (ベージュ)  
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)

アクチュエータ : ポリフェニレンサルファイド ガラス充填, UL94V-0 (黒)  
ACTUATOR POLYPHENYLENE SULFIDE GLASS FILLED, UL94V-0(BLACK)

ターミナル : リン青銅 (t=0.18)  
TERMINAL PHOSPOR BRONZE

金具 : リン青銅 (t=0.15)  
FITTING NAIL PHOSPOR BRONZE

2. メッキ仕様 PLATING

ターミナル TERMINAL  
ニッケル下地鍍ビスマスメッキ  
TIN-BISMUTH (LEAD FREE) OVER NICKEL PLATING

金具 FITTING NAIL  
ニッケル下地鍍メッキ  
PURE TIN (LEAD FREE) OVER NICKEL PLATING

3. インボステーブ梱包時は、アクチュエータが閉じた状態とする。  
IN THE PACKAGE, ACTUATOR OF PART NO.51441-\*\*\*II SHOULD BE CLOSED.
- △ソルダーテール及び金具の平坦度は、0.1以下。  
SOLDER TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.
- △偶数極に適用。  
APPLY FOR EVEN CIRCUIT.
- △パターンはくり止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF PCB PATTERN.
7. この製品は 51441-\*\*\*II 及び 51441-\*\*\*3I の鉛フリー品です。  
THIS PRODUCT IS LEAD FREE ITEM OF 51441-\*\*\*II AND 51441-\*\*\*3I.

FPC/FFCについて:

打抜き方向は導体側から補強板側を推奨いたします。  
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨いたします。  
ABOUT FPC/FFC  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER

FPCについて:

補強フィルム材質はポリイミドを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
ABOUT FPC  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16 DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		51441-***41		MODEL NO.		
	10 UNDER ±0.2		DRAWN BY DATE M. HAYASHI 2003/12/22		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOJO 2003/12/22		TITLE 0.5 FPC CONN. E/O HSG ASSY BTM CONT(H=1.1) -LEAD FREE-				
	30 OVER ±0.3		APPROVED BY DATE M. SASAO 2003/12/22						
	ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-51441-007		2 OF 2		
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				MOLEX INCORPORATED	